PART INFORMATION	
Mfg Item Number	FXPQ3115BV
Mfg Item Name	LGA 8 3*5*1.1 P1.25

SUPPLIER	
Company Name	Freescale Semiconductor Inc
Company Unique ID	14-141-7928
Response Date	2018-06-04
Response Document ID	007KA1.3
Contact Name	Freescale Semiconductor Inc
Contact Title	Product Technical Support
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Representative Title	EPP Customer Response
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Representative Email	eppanlst@freescale.com
URL for Additional Information	www.freescale.com

DECLARATION	
EU RoHS	Yes
Pb Free	No
HalogenFree	Yes
Plating Indicator	
EU RoHS Exemption(s)	7c-I

MANUFACTURING	
Mfg Item Number	FXPQ3115BV
Mfg Item Name	LGA 8 3*5*1.1 P1.25
Version	ALL
Weight	0.031500
UoM	g
Unit Volume	EACH
J-STD-020 MSL Rating	1
Peak Processing Temperature	260 C
Max Time at Peak Temperature	40 seconds
Number of Processing Cycles	3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s),the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
Exemptions in this part	7c-I:Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
List of Freescale Accepted Exemptions	6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight 6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight 6(c) : Copper alloy containing up to 4% lead by weight 7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead) 7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications 7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound 7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher 7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC 7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors 15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages

MATERIAL COMPOSITION

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%		ARTICLEPPM	ARTICLE%
Epoxy Die Attach	0.0002						g					
Epoxy Die Attach		Cadmium/Cadmium Compounds	Cadmium	7440-43-9		0	g	3	0.0003		0	0
Epoxy Die Attach		Plastics/polymers	Phenolic Polymer Resin, Epikote 155	9003-36-5		0.00001319	g	65969	6.5969		418	0.0418
Epoxy Die Attach		Lead/Lead Compounds	Lead	7439-92-1		0.00000002	g	104	0.0104		0	0
Epoxy Die Attach		Plastics/polymers	4,4'-Dihydroxydiphenyl	92-88-6		0.0000022	g	10995	1.0995		69	0.0069
Epoxy Die Attach		Plastics/polymers	Phenol p-xylylene dimethyl ether copolymer	26834-02-6		0.0000022	g	10995	1.0995		69	0.0069
Epoxy Die Attach		Metals	Silver, metal	7440-22-4		0.00018239	g	911934	91.1934		5790	0.579
Bonding Agent	0.0006						g					
Bonding Agent		Plastics/polymers	Plastic: SI - Silicone Rubber	-		0.00047984	g	799734	79.9734		15233	1.5233
Bonding Agent		Glass	Dimethyl silicone polymer with silica	67762-90-7		0.00011996	g	199933	19.9933		3808	0.3808
Bonding Agent		Metals	Other platinum compounds	-		0.0000002	g	333	0.0333		6	0.0006
Bonding Wire, Other	0.0001						g					
Bonding Wire, Other		Metals	Gold, metal	7440-57-5		0.000099	g	990000	99		3142	0.3142
Bonding Wire, Other		Metals	Palladium, metal	7440-05-3		0.000001	g	10000	1		31	0.0031
Organic Substrate	0.0085						g					
Organic Substrate		Metals	Proprietary Material-Other aluminum compounds	-		0.00000116	g	136	0.0136		36	0.0036
Organic Substrate		Metals	Barium sulfate	7727-43-7		0.00022954	g	27005	2.7005		7286	0.7286
Organic Substrate		Metals	Copper, metal	7440-50-8		0.00319514	g	375899	37.5899		101433	10.1433
Organic Substrate		Plastics/polymers	Epikote 862	28064-14-4		0.00057674	g	67852	6.7852		18309	1.8309
Organic Substrate		Plastics/polymers	Proprietary Material-Other Epoxy resins	-		0.00047292	g	55638	5.5638		15013	1.5013
Organic Substrate		Metals	Gold, metal	7440-57-5		0.00009228	g	10856	1.0856		2929	0.2929
Organic Substrate		Metals	Talc	14807-96-6		0.00002653	g	3121	0.3121		842	0.0842
Organic Substrate		Nickel (external applications only)	Nickel	7440-02-0		0.00057674	g	67852	6.7852		18309	1.8309
Organic Substrate		Plastics/polymers	Phenol, polymer with formaldehyde	9003-35-4		0.00031144	g	36640	3.664		9886	0.9886
Organic Substrate		Glass	Fibrous-glass-wool	65997-17-3		0.00191016	g	224725	22.4725		60640	6.064
Organic Substrate		Glass	Silicon dioxide	7631-86-9		0.00017071	g	20084	2.0084		5419	0.5419
Organic Substrate		Metals	Aluminum Hydroxide	21645-51-2		0.00093548	g	110056	11.0056		29697	2.9697
Organic Substrate		Metals	Copper phthalocyanine	147-14-8		0.00000116	g	136	0.0136		36	0.0036
Cap/Cover	0.0137						g					
Cap/Cover		Metals	Chromium, metal	7440-47-3		0.00249596	g	182187	18.2187		79236	7.9236
Cap/Cover		Solvents, additives, and other materials	Phosphorus, elemental (not containing red allotrope)	7723-14-0		0.00000274	g	200	0.02		86	0.0086
Cap/Cover		Solvents, additives, and other materials	Silicon	7440-21-3		0.00007131	g	5205	0.5205		2263	0.2263
Cap/Cover		Metals	Iron, metal	7439-89-6		0.00987241	g	720614	72.0614		313433	31.3433
Cap/Cover		Metals	Manganese, metal	7439-96-5		0.00014948	g	10911	1.0911		4745	0.4745
Cap/Cover		Nickel (external applications only)	Nickel	7440-02-0		0.00110262	g	80483	8.0483		35003	3.5003
Cap/Cover		Solvents, additives, and other materials	Carbon	7440-44-0		0.00000548	g	400	0.04		173	0.0173
Silicon Semiconductor Die	0.004						g					
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%).	-		0.00008	g	20000	2		2539	0.2539
Silicon Semiconductor Die		Glass	Silicon, doped	-		0.00392	g	980000	98		124444	12.4444
Pb Glass Frit Semiconductor Di	0.004				7c-I		g					
Pb Glass Frit Semiconductor Di		Lead/Lead Compounds	Lead (II) titanate	12060-00-3		0.00004152	g	10381	1.0381		1318	0.1318
Pb Glass Frit Semiconductor Di		Glass	Fibrous-glass-wool	65997-17-3		0.00003977	g	9943	0.9943		1262	0.1262
Pb Glass Frit Semiconductor Di		Solvents, additives, and other materials	2,2,4-trimethyl-1,3-pentanediol-1-monoisobutyrate	25265-77-4		0.00003977	g	9943	0.9943		1262	0.1262
Pb Glass Frit Semiconductor Di		Glass	Silicon, doped	-		0.00387894	g	969733	96.9733		123140	12.314
Gel Die Encapsulant	0.0002						g					
Gel Die Encapsulant		Solvents, additives, and other materials	Silicone gum	67762-94-1		0.000094	g	470000	47		2984	0.2984
Gel Die Encapsulant		Solvents, additives, and other materials	Polydimethyl silicones and siloxanes	63148-62-9		0.000104	g	520000	52		3301	0.3301
Gel Die Encapsulant		Solvents, additives, and other materials	Platinum, 1,3-diethenyl-1,1,3,3-tetramethyldisiloxane complexes	68478-92-2		0.000002	g	10000	1		63	0.0063
Gel Die Encapsulant	0.0002						g					
Gel Die Encapsulant		Solvents, additives, and other materials	Silicone gum	67762-94-1		0.000085	g	425000	42.5		2698	0.2698
Gel Die Encapsulant		Solvents, additives, and other materials	Polydimethyl silicones and siloxanes	63148-62-9		0.000095	g	475000	47.5		3015	0.3015
Gel Die Encapsulant		Solvents, additives, and other materials	Dimethyl,methyl hydrogen siloxane	68037-59-2		0.00002	g	100000	10		634	0.0634

LINKS	
MCD LINK	
NXP website	http://www.nxp.com
GENERAL ENVIRONMENTAL COMPLIANCE LINKS	
RoHS signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf
China RoHS	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY
REACH signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf
ELV signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf
Conflict Minerals statement	http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf
NXP ENVIRONMENTAL INFORMATION	
Environmental Compliance website	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX
FAQ	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ
Technical Service Request	http://www.nxp.com/support/sales-and-support:SUPPORTHOME
LINKS TO BLANK IPC1752 FORMS	
Blank IPC1752 v1.1 Form	http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf

IPC1752 XML LINKS

http://www.freescale.com/mcds/FXPQ3115BV_IPC1752_v11.xml

http://www.freescale.com/mcds/FXPQ3115BV_IPC1752A.xml